

1.本站收集的数据手册和产品资料都来自互联网,版权归原作者所有。如读者和版权方有任 何异议请及时告之,我们将妥善解决。

本站提供的中文数据手册是英文数据手册的中文翻译,其目的是协助用户阅读,该译文无法自动跟随原稿更新,同时也可能存在翻译上的不当。建议读者以英文原稿为参考以便获得更精准的信息。

3.本站提供的产品资料,来自厂商的技术支持或者使用者的心得体会等,其内容可能存在描 叙上的差异,建议读者做出适当判断。

4.如需与我们联系,请发邮件到marketing@iczoom.com,主题请标有"数据手册"字样。

Read Statement

1. The datasheets and other product information on the site are all from network reference or other public materials, and the copyright belongs to the original author and original published source. If readers and copyright owners have any objections, please contact us and we will deal with it in a timely manner.

2. The Chinese datasheets provided on the website is a Chinese translation of the English datasheets. Its purpose is for reader's learning exchange only and do not involve commercial purposes. The translation cannot be automatically updated with the original manuscript, and there may also be improper translations. Readers are advised to use the English manuscript as a reference for more accurate information.

3. All product information provided on the website refer to solutions from manufacturers' technical support or users the contents may have differences in description, and readers are advised to take the original article as the standard.

4. If you have any questions, please contact us at marketing@iczoom.com and mark the subject with "Datasheets".



SPECIFICATION



- Supplier : Samsung electro-mechanics
- Product : Multi-layer Ceramic Capacitor
- Samsung P/N : CL05B102KB5NCNC
- Description : CAP, 1nF, 50V, ±10%, X7R, 0402

A. Samsung Part Number

			<u>CL</u>	<u>05</u>	<u>B</u>	<u>102</u>	<u>K</u>	<u>B</u>	<u>5</u>	<u>N</u>	<u>C</u>	<u>N</u>	<u>C</u>				
			1	2	3	4	5	6	\bigcirc	8	9	10	1				
								-									
Û	Series	Samsung Multi-layer Ceramic Capacitor															
2	Size	0402 ((inch c	ode)		L:	1.0	± 0.0	5	mm		W:	0.5	± 0.05	mn	า	
3	Dielectric	X7R					8	Inne	r ele	ctrod	е		Ni				
4	Capacitance	1	nF					Tern	ninat	ion			Cu				
5	Capacitance	±10 9	%					Plati	ng				Sn 10	0%	(Pb	Free)	
	tolerance						9	Prod	luct				High-	Q			
6	Rated Voltage	50 \	V				10	Spec	cial				Reser	ved for	futu	re use	
\bigcirc	Thickness	0.5 =	± 0.05	mm			1	Pack	cagir	ng			Cardb	oard Ty	ype,	7" ree	

B. Samsung Reliablility Test and Judgement condition

	Performance	Test condition							
Capacitance	Within specified tolerance	1ktz±10% 1.0±0.2Vrms							
Tan δ (DF)	0.025 max.								
Insulation	10,000Mohm or 500Mohm· <i>µ</i> F	Rated Voltage 60~120 sec.							
Resistance	Whichever is Smaller								
Appearance	No abnormal exterior appearance	Microscope (×10)							
Withstanding	No dielectric breakdown or	250% of the rated voltage							
Voltage	mechanical breakdown								
Temperature	X7R								
Characterisitcs	(From -55 °C to 125 °C, Capacitance change shoud be within ±15%)								
Adhesive Strength	No peeling shall be occur on the	500g·F, for 10±1 sec.							
of Termination	terminal electrode								
Bending Strength	Capacitance change : within ±12.5%	Bending to the limit (1mm)							
		with 1.0mm/sec.							
Solderability	More than 75% of terminal surface	1) Sn63Pb37 solder							
	is to be soldered newly	235±5℃, 5±0.5sec.							
		2) SnAg3.0Cu0.5 solder							
		245±5℃, 3±0.3sec.							
		(preheating : 80~120°C for 10~30sec.)							
Resistance to	Capacitance change : within ±7.5%	Solder pot : 270±5℃, 10±1sec.							
Soldering heat	Tan δ, IR : initial spec.								

	Performance	Test condition					
Vibration Test	Capacitance change : within ±5%	Amplitude : 1.5mm					
	Tan δ, IR : initial spec.	From 10Hz to 55Hz (return : 1min.)					
		2hours \times 3 direction (x, y, z)					
Humidity	Capacitance change : within ±12.5%	40±2℃, 90~95%RH, 500+12/-0hrs					
	Tan δ : 0.05 max						
	IR : 1000Mohm or 50Mohm $\cdot \mu F$						
	Whichever is Smaller						
Moisture	Capacitance change : within ±12.5%	With rated voltage					
Resistance	Tan δ : 0.05 max	40±2℃, 90~95%RH, 500+12/-0hrs					
	IR : 500Mohm or 25Mohm · <i>μ</i> F						
	Whichever is Smaller						
High Temperature	Capacitance change : within ±12.5%	With 200% of the rated voltage					
Resistance	Tan δ : 0.05 max	Max. operating temperature					
	IR : 1000Mohm or 50Mohm $\cdot \mu F$						
	Whichever is Smaller	1000+48/-0hrs					
Temperature	Capacitance change : within ±7.5%	1 cycle condition					
Cycling	Tan δ, IR : initial spec.	Min. operating temperatur \rightarrow 25 °C					
		\rightarrow Max. operating temperature \rightarrow 25 °C					
		5 cycle test					

C. Recommended Soldering method :

Reflow (Reflow Peak Temperature : 260+0/-5 $^\circ\!\!\mathrm{C}$, 10sec. Max)

* For the more detail Specification, Please refer to the Samsung MLCC catalogue.